

**Paricon Customer Application Requirement**      **Date:**

<b>Company Name:</b>	_____	<b>Program Application Name:</b>	_____
<b>Company Address:</b>	_____	<b>Country:</b>	_____
<b>Comp. Website</b>	_____	<b>Postal Code:</b>	_____
<b>Contact Name:</b>	_____	<b>Telephone Number:</b>	_____
<b>Email Address:</b>	_____	<b>Fax Number:</b>	_____

**Sales Contact:**

**Area of Application** (Development, ProductionTest, Burn-in, OEM ect.):

**Customers Issues**      Overview of the problem that the customer is trying to solve.

**Tech Requirements**

Pitch	Board material and plating:
Contact type (BGA/LGA):	Is there solder mask:-
Contact plating:	Pad geometry:
Package type:	Pad plating:
Device or other key dimensions:	Cycle life expectancy:
Frequency:	Mechanical or dimensional constraints:
Operating Temperature Range:	Can customer redesign board Y/N:
Heat dissipation requirements:	Comments:
Handler or bench top:	
Clamping details:	
Special needs:	
Environmental test requirements:	

**Commercial Requirments**      NDA required Y/N:      Date of NDA:

Prototypes required Y/N	<b>Additional Info:</b>
Proto Quantity:	
Quote req'd by:	
Evaluation period:	
Expected feedback on prototypes/samples:	
Prod Qty potential:	
Target price for prod units:	
Estimated Order Date:	

Technically Approved By:	Paricon Techni	Commercially Approved By
Date:		Date